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### PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

# **CONVEYING PARTY DATA**

Name	Execution Date
Yan-Heng Chen	05/03/2012
Jung-Pang Huang	05/03/2012
Hsin-Yi Liao	05/03/2012
Shih-Kuang Chiu	05/03/2012
Guang-Hwa Ma	05/03/2012

### RECEIVING PARTY DATA

Name:	Siliconware Precision Industries Co., Ltd.	
Street Address:	No. 123, Sec. 3, Da Fong Road, Tantzu	
City:	Taichung	
State/Country:	TAIWAN	

# PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13563052

### **CORRESPONDENCE DATA**

6172274420 Fax Number: Phone: 617 239-0100

Email: cscherbel@edwardswildman.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via

US Mail.

Correspondent Name: **EDWARDS WILDMAN PALMER LLP** 

Address Line 1: P.O. BOX 55874

Address Line 4: **BOSTON, MASSACHUSETTS 02205** 

ATTORNEY DOCKET NUMBER:	91188(71987)
NAME OF SUBMITTER:	Peter F. Corless

**Total Attachments: 1** 

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**PATENT** REEL: 028688 FRAME: 0808

# ASSIGNMENT OF U.S. PATENT APPLICATION

In consideration of the sum of One Dollar in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned (1) Yan-Heng CHEN (2) Jung-Pang HUANG Inventor(s) (3) Hsin-Yi LIAO (4) Shih-Kuang CHIU Full Name(s) (5) Guang-Hwa MA Hereby sell, assign and transfer to SILICONWARE PRECISION INDUSTRIES CO., LTD. Assignee Name and Address No. 123, Sec. 3, Da Fong Road, Tantzu, Taichung, Taiwan, R.O.C. (hereinafter called the Assignee) the entire right, title, and interest in and to any and all improvements which are disclosed in the Application for United States Letters Patent entitled Title of Invention: SEMICONDUCTOR PACKAGE, PACKAGE STRUCTURE AND FABRICATION METHOD THEREOF Which application was Complete either a) executed by the undersigned on \_\_\_\_\_ b) filed on the Serial No. Including any and all United States Letters Patents which may be granted therefore and any and all extensions, divisions, reissues, substitutes, renewals or continuations thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property. It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said assignee. Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, renewal, and reissue patent applications; execute all rightful other papers; and generally do everything possible which said Assignee shall consider desirable for aiding in securing and maintaining proper patent protection. Date Signed at TAIWAN, R.O.C. Inventor(s) Yan-Heng CHEN Full Signature(s) Jung-Pang HUANG Hsin-Yi LIAO Shih-Kuang CHIU Guang-Hwa MA

> PATENT REEL: 028688 FRAME: 0809

RECORDED: 07/31/2012